

CONDUCTIVE LID AND METHOD OF EMPLOYING
A CONDUCTIVE LID IN AN INTEGRATED CIRCUIT

ABSTRACT

The embodiments of the present invention relate to a conductive lid for an integrated circuit having through-holes. The holes may be made anywhere along the epoxy dispense area to improve the strength of the bond between the conductive lid and the substrate of the integrated circuit. The holes preferably extend from the bottom of the conductive lid which is bonded to the package through to the top of the conductive lid. Although straight holes can also be utilized, the holes may be tapered in shape with the top bigger and the bottom smaller in diameter. Methods of securing a conductive lid to an integrated circuit by receiving an adhesive in a through-hole, and using a conductive lid having a through-hole to conduct heat from an integrated circuit are also disclosed.